

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
MICHAEL P. FIELD	06/07/2019
MYUNG HWAN KIM	06/11/2019
RECEIVING PARTY DATA	
Name:	ELEMENTAL SCIENTIFIC, INC.
Street Address:	7277 WORLD COMMUNICATIONS DRIVE
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State/Country:	NEBRASKA
Postal Code:	68122
PROPERTY NUMBERS Total: 2	
Property Type	Number
Application Number:	62654022
Application Number:	16376524
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	10018.0120USU1
NAME OF SUBMITTER:	KEVIN E. WEST
SIGNATURE:	/ kevin e. west /
DATE SIGNED:	09/23/2019
Total Attachments: 2	
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ASSIGNMENT AGREEMENT

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I/We, Michael P. Field, residing at 12402 S. 79th Ave., Papillion, NE 68046; and Myung Hwan Kim, residing at 15067 Meredith Av., Omaha, NE 68116, hereby sell, assign and transfer to Elemental Scientific, Inc., a corporation of the State of Nebraska, having an office at 7277 World Communications Drive, Omaha, NE 68122, and its successors, assigns and legal representatives (collectively "Assignee"), the entire right, title and interest, for the United States and all foreign countries, in and to any and all inventions and improvements ("Inventions") as described and/or claimed in a provisional application for Letters Patent of the United States entitled SYSTEM WITH REUSABLE COLUMN WITH RESIN PACKING AND UNPACKING PROCEDURES AND SAMPLE ANALYSIS, Application No. 62/654,022 filed April 6, 2018, and/or an application for Letters Patent of the United States of America entitled SYSTEM WITH REUSABLE COLUMN WITH RESIN PACKING AND UNPACKING PROCEDURES AND SAMPLE ANALYSIS, Application No. 16/376,524 filed on April 5, 2019, and in and to the applications and all divisional, continuing, substitute, renewal, reissue, reexamination and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries for the Inventions, and all the rights and privileges under any and all Letters Patent that may be granted therefore including any reissues, reexaminations and extensions thereof.

I/We agree that when requested will, without charge to Assignee but at its expense, sign all papers, take all rightful oaths, make all rightful declarations and do all acts which may be necessary, desirable or convenient for securing and maintaining patents or other forms of protection for the Inventions in any and all countries and for vesting title thereto in Assignee.

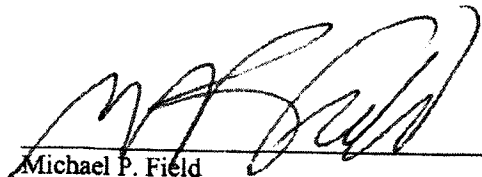
I/We authorize and empower Assignee to make applications for patent or other form of protection for the Inventions in Assignee's own name in any and all countries, and to invoke and claim for any application for patent or other form of protection for the Inventions filed by Assignee the benefit of all rights of priority provided by any and all treaties, conventions or agreements without further written or oral authorization.

I/We hereby consent that a copy of this Assignment Agreement shall be deemed a full legal and formal equivalent of any assignment, consent to file or similar document which may be required in any

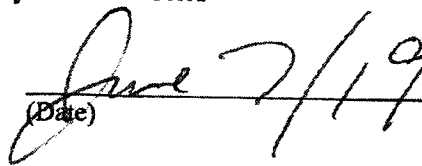
Docket No. 10018.0120USU1

country for any purpose, including proof of the right of Assignee to apply for patent or other form of protection for the Inventions and to claim the aforesaid benefit of the right of priority.

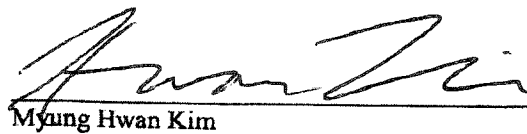
IN WITNESS WHEREOF, I/we have hereunto signed my/our name(s) on the day and year set forth below.




Michael P. Field



(Date)



Myung Hwan Kim



(Date)